

化工全球系列报告之十三

硅微粉深度报告： 下游需求持续增加，品质要求不断提高

Both Downstream Demand and Quality Requirements are increasing

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投资要点

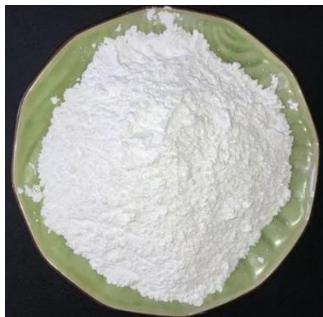
- **硅微粉是一类用途广泛的无机非金属材料。**硅微粉是将高纯度的石英矿通过物理或化学方法破碎、粉碎而得到的微米级别的粉末，其颗粒大小一般在1-100微米之间，常用的颗粒大小为5微米左右，而随着半导体制程的进步，1微米以下的硅微粉也逐渐得到广泛采用。硅微粉具有介电性能优异、热膨胀系数低、导热系数高、化学稳定性高、耐高温、硬度高等一系列优点，因此被广泛应用于半导体、电子、化工、医药等领域。
- **高端领域多使用球形硅微粉。**硅微粉按照其颗粒形态一般可分为角形硅微粉和球形硅微粉，角形硅微粉又常按结晶特点分为结晶硅微粉和熔融硅微粉，球形硅微粉通常是在这两种角形硅微粉的基础上，通过火焰成球等方法进一步制备而来。同角形硅微粉相比，球形硅微粉流动性好，在树脂中的填充量较高，做成板材后内应力低、尺寸稳定、热膨胀系数低，并且具有更高的堆积密度和更均匀的应力分布，同时还可减少相关制品制造时对设备和模具的磨损，因而在对性能要求较高的高端领域得到了迅速的应用。
- **高球化率、高纯度、超细化是球形硅微粉的未来方向。**球化率是衡量球形硅微粉品质的重要指标之一，球化率越高，硅微粉的流动性及分散性能就越好，在树脂中的分布就越均匀，同时对模具的磨损程度就越小；高纯度是电子产品对材料最基本的要求，在超大规模集成电路中的要求则更加严格，除了常规杂质元素含量要求低外，还要求放射性元素含量尽量低或没有，否则对电信号的传输速度及质量都会带来负面的影响；球形硅微粉的热传导率不如结晶硅微粉，而超大规模集成电路由于发热量巨大对散热性能的要求较高，超细化硅微粉由于导热性更好而能部分的解决这个问题。
- **预期全球硅微粉市场2027年将可达53.3亿美元。**随着电动汽车及数据中心增长带来的对电子元器件需求的增长，我们预期2027年全球硅微粉市场将有望达到53.3亿美元，年均复合增长率约为5.1%。
- **硅微粉需求有望受益于ChatGPT的兴起。**ChatGPT的部署及训练需要大量的算力及存储空间，会带来对逻辑芯片及存储芯片的大量需求，尤其是对先进制程芯片的需求。作为半导体工业中重要上游原材料的硅微粉，尤其是适用于先进制程封装的高端硅微粉，将有望受益。
- **重点公司。**国际公司目前仍在高端硅微粉市场占据主要地位，其市场份额及技术均较为领先，目前正紧跟下游产业需求，不断开发新技术及新产品，建议重点关注电化。国内公司建议关注联瑞新材、飞凯材料、雅克科技。
- **风险。**数据中心增速不及预期；半导体周期下行时间长于预期；车载电子增速不及预期。

1.1 硅微粉：用途广泛的无机填充料

- 硅微粉是一类用途广泛的无机非金属材料，其介电性能优异、热膨胀系数低、导热系数高。系列产品是以纯净石英粉为原料，经一系列物理或化学工艺加工而成，常见的产品有结晶硅微粉、熔融硅微粉、球形硅微粉等。它具有白度高、颗粒细、粒度分布合理、比表面积大、悬浮性能优、纯度高等优点，广泛用于涂料、油漆、胶粘剂、硅橡胶、精密铸造、高档陶瓷、环氧树脂灌封料及普通电器、高压元器件的绝缘浇注、集成电路的塑封料和灌封料、粉末涂料、电焊条保护层及其它树脂填料等。

图：硅微粉产品

结晶硅微粉



熔融硅微粉



球形硅微粉



资料来源：龙森，海通国际

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1.2 硅微粉：常按颗粒形态分为角形与球形

- 根据不同的分类标准，硅微粉分为不同的类型，如按照用途和纯度可分为普通硅微粉、电工级硅微粉、电子级硅微粉、半导体级硅微粉等，按照结晶特点可分为结晶硅微粉、熔融硅微粉等；按照颗粒形态可分为角形硅微粉、球形硅微粉等。目前业界常采用结晶特点以及颗粒形态两种分类方法对相关产品进行分类

表：硅微粉的分类与品种

硅微粉的分类	硅微粉的品种
按用途和纯度	普通硅微粉 (>99%)，电工级硅微粉 (>99.6%)，电子级硅微粉 (>99.7%)，半导体级硅微粉 (>99.9%) 等
按化学成分	纯硅微粉，以二氧化硅为主要成分的复合硅微粉
按结晶特点	结晶硅微粉，熔融硅微粉等
按矿物种类	石英硅微粉，方石英硅微粉等
按颗粒形态	角形硅微粉，球形硅微粉等
按粒度大小	目是指每英寸（合2.54cm）筛网上的孔眼数目，如300目就是指每英寸上的孔眼是300个，每平方英寸上的孔眼则为300*300=90000个，故300目对应48μm。常见的粒度大小有300目，400目，600目，800目，1000目，超细硅微粉（通常<4000目）等
按表面活性	普通硅微粉表面改性后成为活性硅微粉，如电工级活性硅微粉等

表：硅微粉产品的粒度分布

规格(目)	中粒粒径 d_{50} (μm)	比表面积(cm^2/g)	累积粒度(μm,%)
300	21.00~25.00	1700~2100	-50≥75
400	16.00~20.00	2100~2400	-39≥75
600	11.00~15.00	2400~3000	-25≥75
1000	8.00~10.00	3000~4000	-10≥65

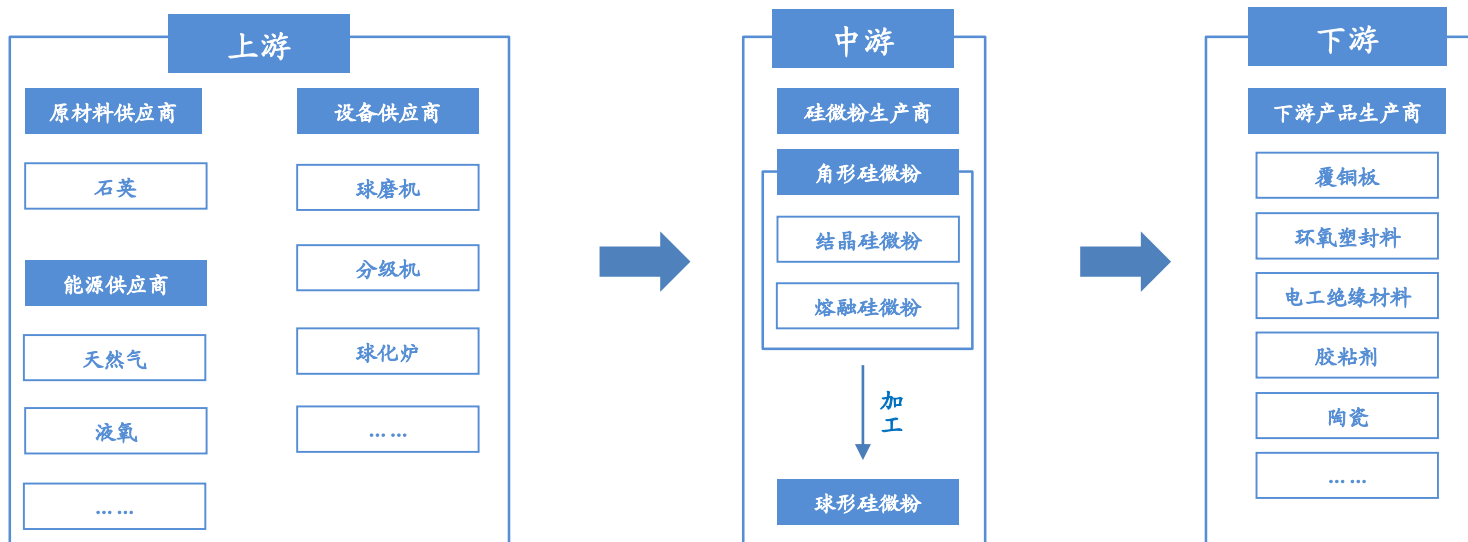
资料来源：粉体技术网，海通国际

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1.2 硅微粉：球形为角形进一步加工而来

- 硅微粉产业上游包括石英等原材料供应商、天然气等能源供应商、球磨机等设备供应商，下游则涵盖覆铜板、环氧塑封料、绝缘材料、胶粘剂、涂料、陶瓷等众多产业。角形硅微粉主要可分为结晶硅微粉及熔融硅微粉两大类，而球形硅微粉则是在角形硅微粉的基础上进一步制备而来。

图：硅微粉产业链



资料来源：华经产业研究院，海通国际

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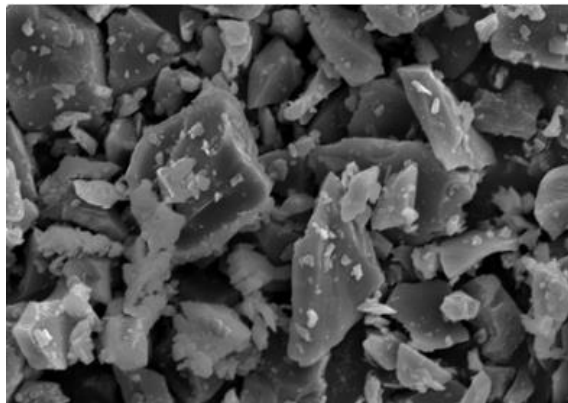
1.2 结晶型硅微粉：工艺简单、成本较低

- 结晶硅微粉的主要原料是精选优质石英矿，经过研磨、精密分级除杂等工序加工而成的二氧化硅粉体材料，能够改善覆铜板等下游产品的线性膨胀系数、电性能等物理性能。其优势在于起步早，工艺成熟并且简单，对生产硬件要求较低且价格相对便宜，对覆铜板的刚度、热稳定性和吸水率等各方面的性能都有不小的改善作用。其缺点主要是对树脂体系的改善不及球形硅微粉，具体表现为分散性、耐沉降性以及耐冲击性均比球形硅微粉要低，热膨胀系数比球形硅微粉要高。

图：结晶型硅微粉外观



图：扫描电子显微镜下的结晶型硅微粉



资料来源：龙森，海通国际

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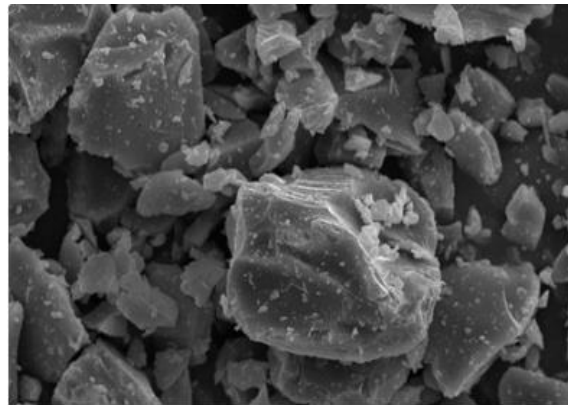
1.2 熔融型硅微粉：性能较好、成本居中

- 熔融硅微粉的主要原料是精选的具有优质晶体结构的石英，经酸浸、水洗、风干、再经高温熔融、破碎、人工分拣，磁选、超细碎、分级等工艺精制而成的硅微粉。同结晶型硅微粉相比，熔融硅微粉具有密度、硬度、介电常数、热膨胀系数等较低的优点，在高频覆铜板中的应用尤为突出，可应用于智能手机、平板电脑、网络通讯等行业，其主要缺点是制备过程中熔融温度较高，工艺复杂，介电常数相对于结晶型硅微粉虽有改善但仍较高，其其生产成本较结晶型硅微粉要高。

图：熔融型硅微粉外观



图：扫描电子显微镜下的熔融型硅微粉



资料来源：龙森，海通国际

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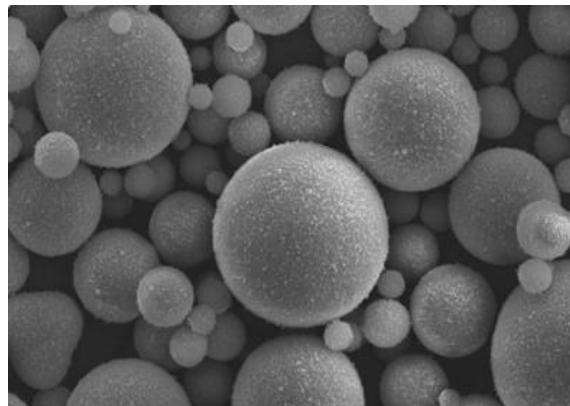
1.2 球形硅微粉：性能好、成本高

- 球形硅微粉是指颗粒个体呈球状，一种高强度、高硬度、惰性的球型颗粒，是通过高温将形状不规则的精选角形硅微粉颗粒瞬间熔融使其在表面的张力作用下球化，后经过冷却、分级、混合等工艺加工而成的硅微粉。球形硅微粉流动性好，在树脂中的填充量较高，做成板材后内应力低、尺寸稳定、热膨胀系数低，并且具有更高的堆积密度和更均匀的应力分布，因此可增加填料中的流动性和降低粘度。此外，球形硅微粉相比角型硅微粉有更大的比表面积，能够显著降低覆铜板和环氧塑封料的线性膨胀系数，提高电子产品的可靠性，同时还可减少相关制品制造时对设备和模具的磨损。其缺点主要是制备工艺复杂，成本较高。

图：球形硅微粉外观



图：扫描电子显微镜下的球形硅微粉



资料来源：龙森，海通国际

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1.3 SJ/T10675 – 2002硅微粉产品分类：电工级及电子级

- 根据国标SJ/T10675-2002，硅微粉可分为：用于电工行业的普通硅微粉(PG)、普通活性硅微粉(PGH)、电工级硅微粉(DG)、电工级活性硅微粉(DGH)。用于电子行业的电子级结晶型硅微粉(JG)、电子级结晶型活性硅微粉(JGH)、电子级熔融型硅微粉(RG)、电子级熔融型活性硅微粉(RGH)。

表：硅微粉产品理化指标

指标	PG	PGH	DG	DGH	JG	JGH	JG	JGH	RG	RGH	RG	RGH	
					优等品		合格品		优等品		合格品		
含水量(%)	≤0.1				≤0.08								
密度(t/m ³)					2.65±0.05				2.20±0.05				
化学成分	LOI	≤0.20		≤0.15			≤0.10				≤0.08		
	SiO ₂	≥99.40		≥99.60		≥99.70		≥99.65		≥99.80		≥99.75	
	Fe ₂ O ₃	≤0.030		≤0.020			≤0.010				≤0.008		
	Al ₂ O ₃	≤0.20		≤0.15			≤0.10				-		
	憎水性(min)	-	≥30	-	≥45	-	≥45	-	≥45	-	≥45	-	≥45
	无定形SiO ₂					-				≥98		≥95	
水萃取液	电导率(μs/cm)	-		≤30	≤5	≤10	≤10	≤15	≤5	≤10	≤10	≤15	
	Na+(*10 ⁻⁶)	-		≤20	≤2	≤3	≤5	≤8	≤2	≤3	≤5	≤8	
	Cl-(*10 ⁻⁶)	-		≤20	≤2	≤3	≤5	≤8	≤2	≤3	≤5	≤8	
	pH值		-				6.5~8.0				5.5~7.5		

资料来源：国家标准化管理委员会，海通国际

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1.3 三种硅微粉对比：因参数不同而细分应用领域不同

- 三种硅微粉因其参数不同而细分应用领域不同。总体来说，应用领域按照结晶硅微粉、熔融硅微粉、球形硅微粉的次序而逐渐高端化。结晶硅微粉常见于电工级应用领域，如家电用覆铜板、开关、接线板、充电器等；熔融硅微粉常被应用于电子级领域，如智能手机、平板电脑、汽车等使用的覆铜板，芯片封装使用的环氧塑封料、胶粘剂等；球形硅微粉主要用于高端芯片的环氧塑封料制造，高频高速电路用覆铜板的填料等。

表：硅微粉常见理化指标

项目	特性简介	结晶硅微粉	熔融硅微粉	球形硅微粉
填充效果	与颗粒形状具有一定关系，球形颗粒具备滚珠效应，填充率高于角形。填充率越高，填料的填充比例越高	电镜下颗粒为角形	电镜下颗粒为角形	电镜下颗粒为球形
密度	密度越小，越有利于下游产品的轻便化	2.65*10 ³ kg/m ³	2.20*10 ³ kg/m ³	2.20*10 ³ kg/m ³
莫氏硬度	硬度越大，耐磨性越高	7	6.5	6.5
介电常数	介电常数越小，信号传输速度越快	4.65 (1MHz)	3.88 (1MHz)	3.88 (1MHz)
介质损耗	介质损耗越小，信号传输质量越高	0.0018 (1MHz)	0.0002 (1MHz)	0.0002 (1MHz)
线性膨胀系数	线性膨胀系数越小，材料尺寸随温度变化越小	14*10 ⁻⁶ 1/K	0.5*10 ⁻⁶ 1/K	0.5*10 ⁻⁶ 1/K
热传导率	热传导率越高，散热性能越好	12.6 W/(m·K)	1.1 W/(m·K)	1.1 W/(m·K)

表：三种硅微粉性能及应用领域

参数	结晶硅微粉	熔融硅微粉	球形硅微粉
传热性	好	较好	较好
固化产生的应力	较大	较小	小
填充性	一般	一般	好
固化收缩率	较小	小	小
热膨胀率	较小	较小	较小
磨损性	大	中	小
应用领域	家电用覆铜板、开关、接线板、充电器等使用的环氧塑封料；电工绝缘材料、胶粘剂、涂料、陶瓷等领域	智能手机、平板电脑、汽车、网通及工业设备等所使用的覆铜板；芯片封装使用的环氧塑封料；胶粘剂、涂料、陶瓷、封装等	高端芯片封装用环氧塑封料、高频高速电路用覆铜板等电子材料的高性能填料；高性能涂料、塑料等的性能调节剂；特种陶瓷的烧结助剂

资料来源：联瑞新材，海通国际

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1.4 角形硅微粉的制备：生产设备主要有球磨机、振动磨等

- 角形硅微粉是用硅微粉原材料经研磨而得到的外形无规则多呈棱角状的硅微粉，主要生产设备有球磨机、振动磨、微粉分级机和烘干机等。球磨机是物料被破碎之后，再进行粉碎的关键设备；振动磨则是利用磨矿介质受磨机的振动作用，在磨机腔体内滑动、滚动而对物料进行研磨；微粉分级机利用风机对物料进行分级；烘干机则可以保证硅微粉含水量极低。

图：角形硅微粉主要生产设备

球磨机



振动磨



微粉分级机



烘干机



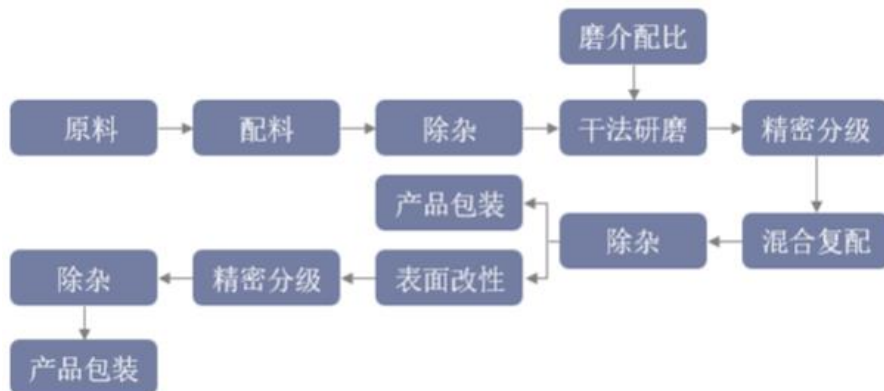
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1.4 角形硅微粉的制备：主要有干法和湿法研磨两种

- 干法研磨是将硅微粉原料放进球磨机或振动磨中研磨，该研磨工艺可以连续进料和出料，也可以一次投入若干重量原料，连续研磨若干时间后出料；出料时要经过微粉分级机控制粒度，粗的产物返回磨机再磨或作为产品，细的则是产品。干法研磨要严格控制入磨物料水分，产品不再干燥。

图：干法研磨工艺



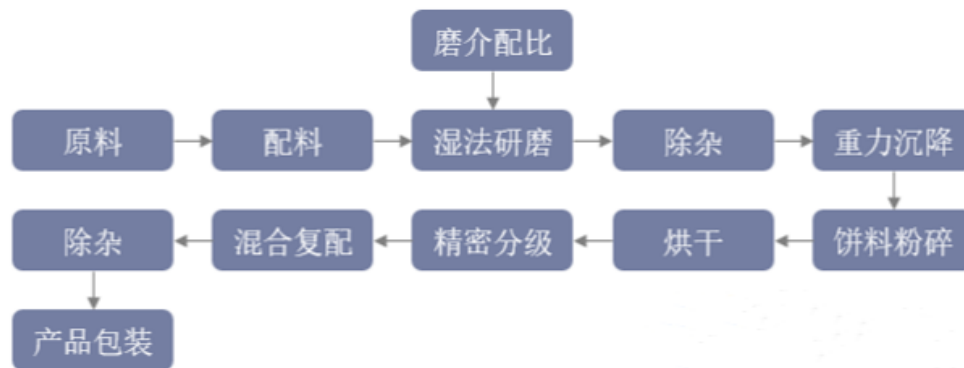
资料来源：华经产业研究院，海通国际

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1.4 角形硅微粉的制备：主要有干法和湿法研磨两种

- ▶ 湿法研磨是将若干重量硅微粉原料一次投入球磨机中，加入适量的水，作业浓度在65%~80%；连续研磨十几个小时后，倒出料浆，用压滤方法或放在料桶内自然沉淀脱水，得到含水料饼；用打碎机打碎分散后均匀连续地投到空心轴搅拌烘干机中，干燥后得到产品。

图：湿法研磨工艺



资料来源：华经产业研究院，海通国际

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1.5球形硅微粉的制备：工业上以物理法为主

- 目前制备球形硅微粉的方法可分为物理法和化学法。物理法制备球形硅微粉，原材料来源广且价格不高，但对原材料石英质量和生产设备等要求较高。其中火焰成球法是一种可实现规模化生产且有发展前景的工艺技术。化学法可制备出高纯且粒径均匀的球形硅微粉，但由于在制备过程中对表面活性剂需求较大，极大增加了生产成本，且存在有机杂质不易除净、容易团聚及工业化难以实现等缺点。目前工业上以物理法制备为主。

表：球形硅微粉常见制备方法

项目	分类	主要方法	特点
球形硅微粉的制备方法	物理法	火焰成球法、高温熔融喷射法、自蔓延低温燃烧法、等离子体法、高温煅烧球形化等	原材料来源广且价格不高，但对原材料石英质量和生产设备等要求较高
	化学法	气相法、水热合成法、溶胶-凝胶法、沉淀法、微乳液法等	可以制备出高纯且粒径均匀的球形硅微粉；制备过程中对表面活性剂需求大，增加了生产成本；有机杂质不易除净、颗粒团聚严重、难以工业化

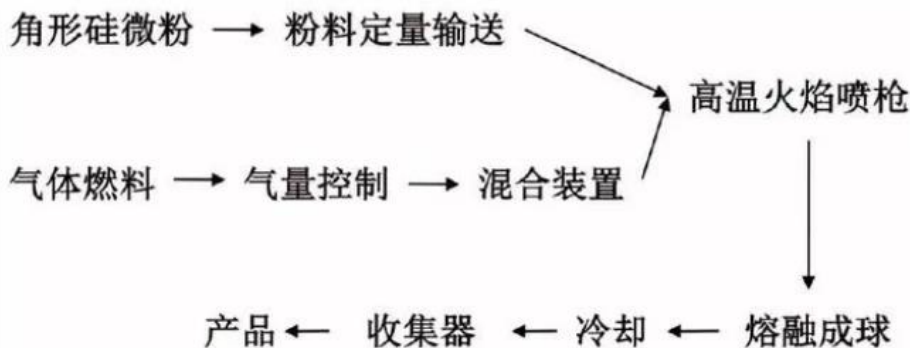
资料来源：长江有色金属网，联瑞新材，海通国际

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1.5 火焰成球法：易于实现工业化大规模生产的主流方法

- ▶ 火焰成球法的工艺流程为：首先对高纯石英砂进行粉碎、筛分和提纯等前处理，然后将石英微粉送入燃气-氧气产生的高温场中，进行高温熔融、冷却成球，最终形成高纯度球形硅微粉。该技术的关键是加热装置要求有稳定的温度场、易于调节温度范围以及不要对石英粉造成二次污染。主要生产设备包括粉料定量输送系统、燃气量控制和混合装置、气体燃料高温火焰喷枪、冷却回收装置等。该法生产工艺简单，有利于进行大规模工业生产，发展前景较好。

图：火焰成球法工艺



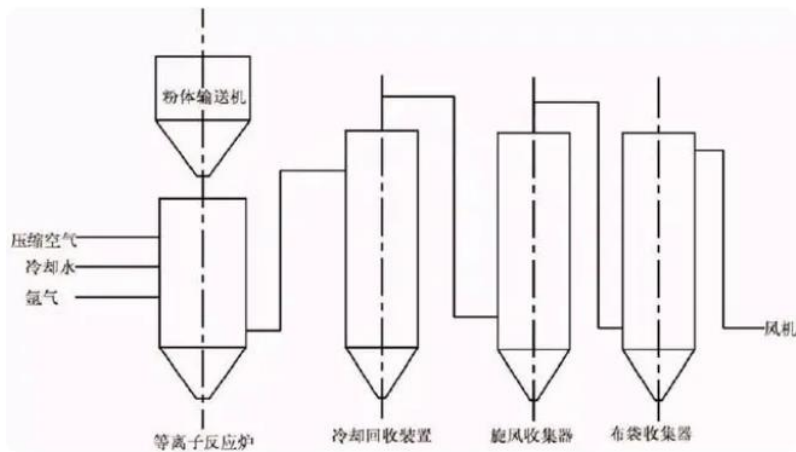
资料来源：粉体技术网，海通国际

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1.5 等离子体法：换热源为等离子体的制备方法

- ▶ 等离子体技术的基本原理是利用等离子炬的高温区将二氧化硅粉体熔化，由于液体表面张力的作用形成球形液滴，然后在快速冷却过程中形成球形化颗粒。采用高频等离子体熔融法制备球形石英粉，温度范围适中、控制平稳、产量高，可达到较高球化率，因而是一种较合适的生产方法。其原理与工艺与火焰熔融法类似，主要是将高温热源变为等离子体发生器。

图：等离子体法工艺



资料来源：粉体技术网，海通国际

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1.6 硅微粉：可用于覆铜板、环氧塑封料、绝缘材料等

- 硅微粉由于具有耐酸碱腐蚀、耐高温、线性膨胀系数低、热传导率高等优点，被广泛应用至覆铜板、环氧塑封料等领域以改善相关产品的性能。如在覆铜板中加入硅微粉可改善其线性膨胀系数和热传导率；在环氧塑封料中加入硅微粉则可以显著提高环氧树脂硬度，增大导热系数，降低环氧树脂固化物反应的放热峰值温度等。

表：常见硅微粉用途简介

项目	性能	主要应用领域	用途
硅微粉	(1) 无机材料，耐酸碱腐蚀，耐高温，化学性能稳定；(2) 高绝缘，制品安全性高；(3) 低线性膨胀系数，制品稳定性高；(4) 良好的热传导率，制品散热性好；(5) 低介电常数和介质损耗，介电性能优异	覆铜板	在覆铜板中加入硅微粉可以改善印刷电路板的线性膨胀系数和热传导率等物理特性，从而有效提高电子产品的可靠性和散热性。
		环氧塑封料	硅微粉填充到环氧塑封料中可显著提高环氧树脂硬度，增大导热系数，降低环氧树脂固化物反应的放热峰值温度，降低线性膨胀系数与固化收缩率，减小内应力，提高环氧塑封料的机械强度，减少环氧塑封料的开裂现象从而有效防止外部有害气体，水分及尘埃进入电子元器件或集成电路，减缓震动，防止外力损伤和稳定元器件参数。
		电工绝缘材料	硅微粉用作电工绝缘产品环氧树脂绝缘封装料，能够有效降低固化物的线性膨胀系数和固化过程中的收缩率，减小内应力，提高绝缘材料的机械强度，从而有效改善和提高绝缘材料的机械性能和电学性能。
		胶粘剂	硅微粉作为无机功能性填充材料，填充在胶粘剂树脂中可有效降低固化物的线性膨胀系数和固化时的收缩率，提高胶粘剂机械强度，改善耐热性、扛渗透性和散热性能，从而提高粘附和密封效果。

资料来源：安米微纳，海通国际

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2.1 覆铜板用硅微粉：球形主要用于高速高频覆铜板

- 目前应用于覆铜板的硅微粉主要有结晶型硅微粉、熔融型（无定型）硅微粉、球形硅微粉、复合硅微粉、活性硅微粉等五个品种。球形硅微粉由于其特有的高填充、流动性好、介电性能优异的特点，主要应用在高填充、高可靠的高性能覆铜板中。覆铜板用球形硅微粉关注的主要指标有：粒径分布、球形度、纯度（电导率、磁性物质和黑点）。目前球形硅微粉主要被用在刚性覆铜板上，占覆铜板的混浇比例一般为20%~30%；挠性覆铜板与纸基覆铜板的使用量相对较小。

表：球形硅微粉在覆铜板行业的主要应用领域

应用领域	重量比	领域特点	使用原因
高速	>25%	关注电性能，认证周期长	优异介电性能
IC封装	>40%	认证时间长，关注大颗粒	高模量、低热膨胀系数
汽车	>20%	认证时间长，关注可靠性	低热膨胀系数、高可靠性
服务器	>25%	关注成本、可靠性	提升多层板可靠性
HDI	>25%	关注模量、关注大颗粒	薄型化，提高模量

表：覆铜板关注的球形硅微粉主要指标

项目	对覆铜板影响	测试标准
粒径分布	薄型化	GB/T 19077.1-2008
比表面积	填充量、流动性	GB/T19587
球形度	填充量、流动性	GB/T 32661-2016
结晶型含量%	介电性	SJ/T 10675-2002
电导率	绝缘性	GB/T 6908
pH	反应性	GB/T 9724
黑点	绝缘性	企业标准
磁性物质含量	绝缘性	GB/T 32661-2016
筛分余量	薄型化	GB/T 32661-2016

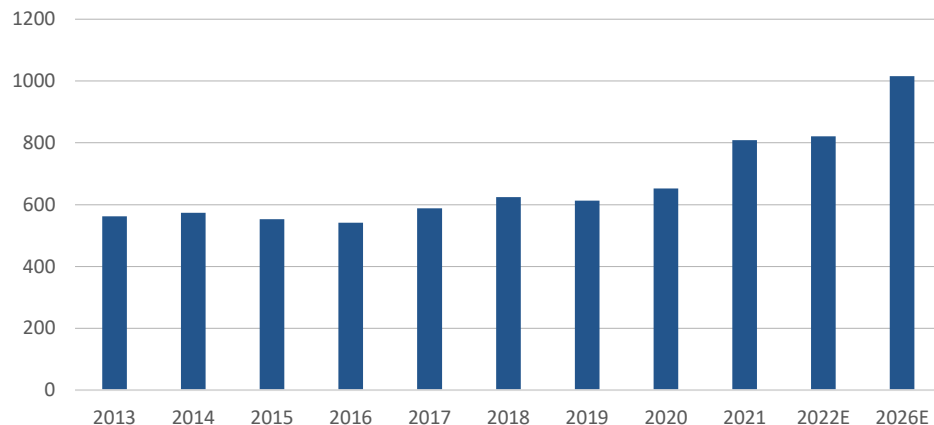
资料来源：中国粉体网，海通国际

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2.1 PCB: 全球市场规模2026年有望达到1016亿美元

- ▶ 印制电路板（PCB）指采用印制技术，在绝缘基材上按预定设计形成导电线路图形或含印制元件的功能板，用于实现电子元器件之间的相互连接和中继传输，是电子信息产品不可缺少的基础元器件，也是覆铜板（CCL）的重要下游应用。由于汽车电子、数据中心的持续景气，叠加消费电子的需求回暖预期，根据Prismark的预测，全球PCB市场规模有望在2026年达到1016亿美元，2021-2026年均复合增长率约4.7%。

图：全球PCB市场规模（亿美元）



数据来源：Prismark，海通国际

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2.1 PCB: 中国大陆产值规模占全球比重超过50%

- 从全球印制电路板(PCB)制造行业区域产值格局来看, 中国大陆、中国台湾、日韩是全球PCB制造行业主要的制造基地。2021年, 中国大陆产值规模达到全球产值的57%, 中国台湾为12%, 韩国及日本分别为10%和8%。按照生产厂商所属国家或地区来看, 2021年全球市占率前十厂商中, 中国台湾占据5席, 市占率合计19.8%; 中国大陆占据2席, 市占率合计6.7%; 日本占据2席, 市占率合计6.3%; 美国占据1席, 市占率2.78%。

图: 2021年全球PCB区域产值格局

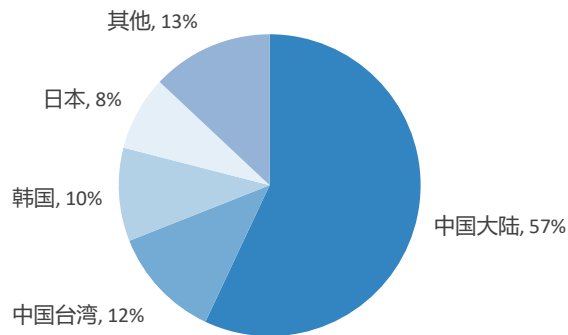
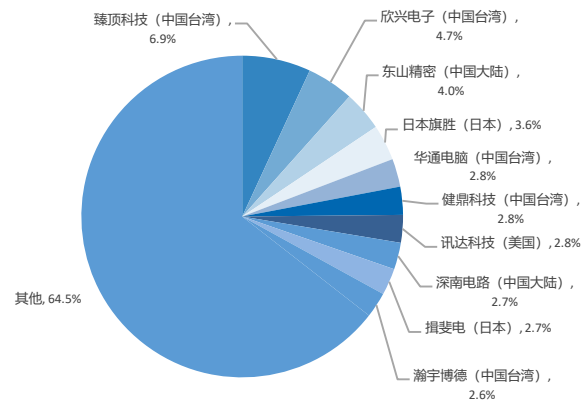


图: 2021年全球PCB行业市占率前十厂商



数据来源: 前瞻产业研究院, Prismark, 海通国际

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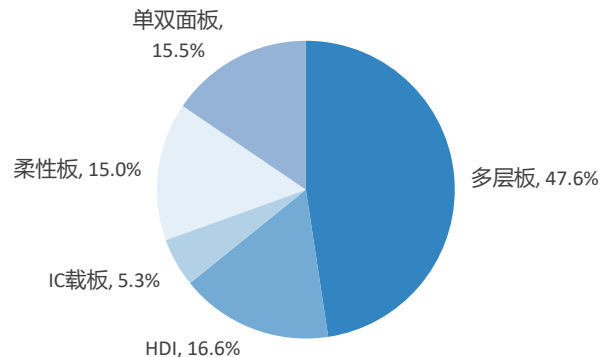
2.1 PCB：HDI及IC载板（封装基板）是未来发展方向

- ▶ PCB根据技术参数大致可分为IC载板、HDI及普通PCB。随着半导体制程的不断进步，电子行业对于精度及性能的要求越来越高，叠加消费电子小型化、轻量化的发展方向，PCB中的高端品类IC载板及HDI的需求不断增加。目前中国PCB行业细分市场结构中，HDI及IC载板的占比依然比较低，未来提升空间较大。

表：普通PCB、HDI、IC载板技术参数比较

技术参数	普通PCB	HDI	IC载板
层数	1~90+	4~16	2~10
板厚	0.3-17mm	0.25-12mm	0.08-11.2mm
最小线宽/线距	50-1000μm	40-160μm	10-130μm
最小环宽	75μm	75μm	12.5-130μm
单位尺寸	-	300mm*210mm	<150mm*150mm
制备工艺	减成法	半加成法/减成法	减成法/半加成法

表：2021中国PCB产业细分市场结构



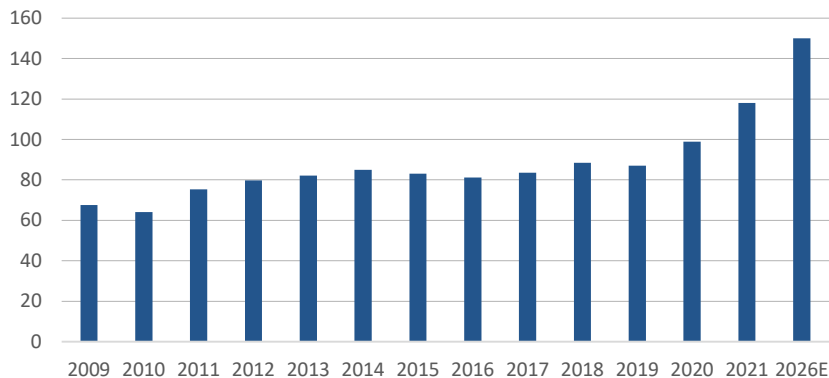
数据来源：华经产业研究院、Prismark，海通国际

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2.1 PCB: 全球HDI市场规模2026年有望达到150亿美元

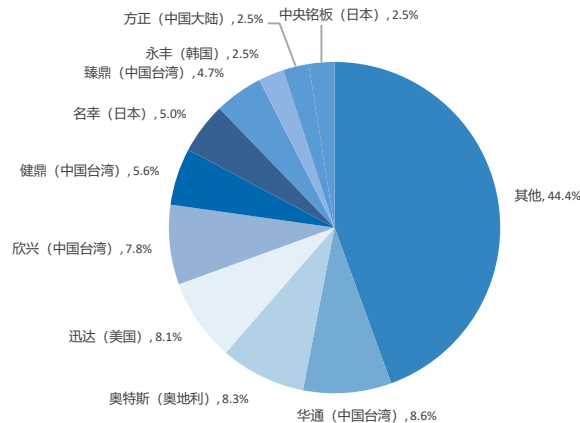
- HDI是使用微盲埋孔技术制作的一类线路分布密度比较高的印刷电路板，可实现更小的孔径、更细的线宽、更少通孔数量，节约PCB可布线面积、大幅度提高元器件密度、改善射频干扰/电磁波干扰/静电释放等，符合电子产品轻薄短小的发展方向。一般来说，同普通PCB板相比，HDI的层数更高，最小线宽更小，对于曝光设备及贴合设备的需求增加，工艺相对于普通PCB板更为复杂。根据Prismark的数据，预计全球HDI市场规模有望在2026年达到150亿美元，2021-2026年均复合增长率约为4.9%。2019年全球市场占有率前十的企业中，中国仅方正占据1席，市场份额约为2.5%。

图：全球HDI市场规模（亿美元）



数据来源：Prismark，海通国际

图：2019年HDI产业竞争格局

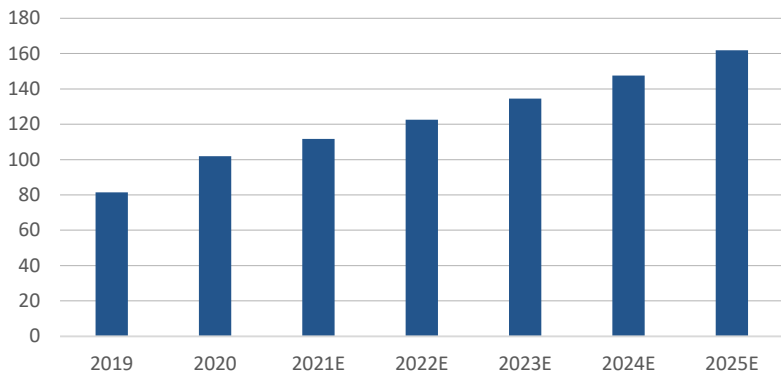


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2.1 PCB: 全球IC载板市场规模2025年有望达到162亿美元

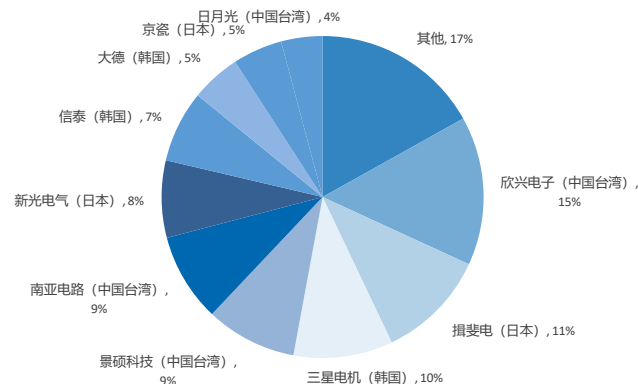
- IC载板即封装基板，是一类用于承载芯片的线路板，属于PCB的一个分支，具有高密度、高精度、高性能、小型化及轻薄化的特点，可为芯片提供支撑、散热和保护的作用，同时也可作为芯片与PCB母板之间提供电气连接及物理支撑。封装基板产品有别于传统PCB，高加工难度与高投资门槛是封装基板的两大核心壁垒。根据Prismark的数据，预计全球IC载板市场规模有望在2025年达到162亿美元，2020-2025年均复合增长率约为9.7%，是PCB各细分市场中成长性最高的市场。2020年全球市场占有率前十的企业均为中国台湾及日韩企业，中国大陆企业暂时缺席。

图：全球IC载板市场规模（亿美元）



数据来源：Prismark，海通国际

图：2020年IC载板产业竞争格局

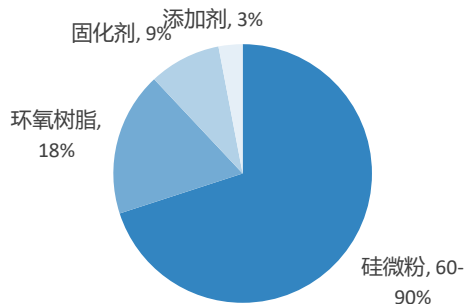


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2.2 环氧塑封料用硅微粉：约占总用料的60%-90%

- 常见的环氧塑封料的主要组成为填充料60-90%，环氧树脂18%以下，固化剂9%以下，添加剂3%左右。现用的无机填料基本上都是硅微粉，其含量最高达90.5%。硅微粉作为填充料具有降低塑封料的热膨胀系数，增加热导，降低介电常数，环保、阻燃，减小内应力，防止吸潮，增加塑封料强度，降低封装料成本等作用。

图：环氧塑封料中各类材料的占比



资料来源：华经产业研究院，海通国际

表：环氧塑封料用硅微粉关注指标

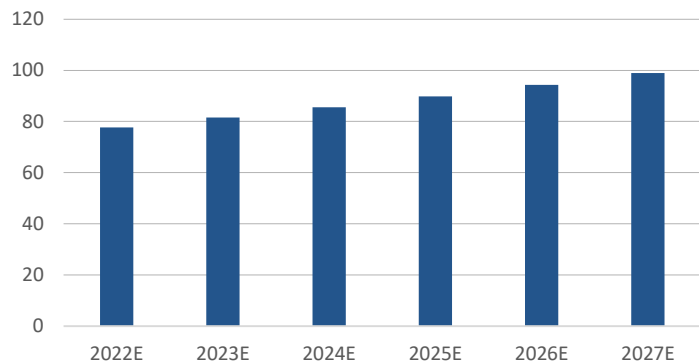
	项目	描述
EMC用硅微粉主要关注指标	纯度	高纯度是电子产品对材料最基本的要求，在超大规模集成电路中要求更加严格，除了常规杂质元素含量要求低外，还要求放射性元素含量尽量低或没有。随着制程的进步，电子行业对硅微粉纯度的要求也越来越高。
	粒度及均匀程度	超大规模集成电路封装材料要求硅微粉粒度细、分布范围窄、均匀性好。美国用于环氧塑封料的硅微粉粒度一般为1-3 μm ，日本平均粒径一般为3-8 μm 。由于粒度更小的硅微粉导热性更好，随着技术的进步，1 μm 及以下粒度的硅微粉开始越来越多的被使用。
	球化率	高球化率是保证填充料高流动性、高分散性的前提，球化率高、球形度好的硅微粉流动性和分散性能更好，在环氧塑封料中能得到更充分的分散进而保证最佳的填充效果。目前国际主流的EMC用硅微粉球化率一般在98%以上。

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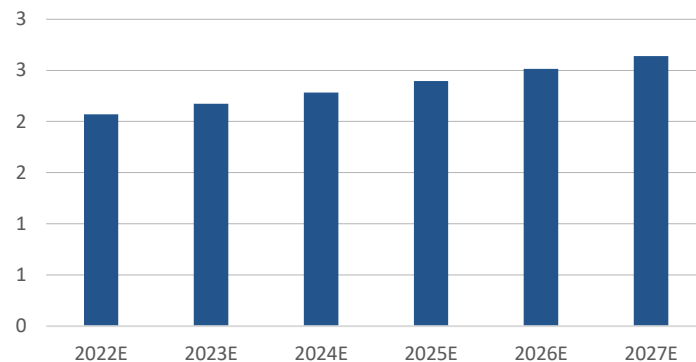
2.2 全球环氧塑封料市场规模2027年有望达到99亿美元

- 根据Mordor Intelligence的数据，2021年全球环氧塑封料市场规模约74亿美元，2027年有望成长至99亿美元，年均复合增长率约5.0%。按照硅微粉占环氧塑封料的成本比例测算，2027年来自环氧塑封料行业对硅微粉的需求有望达到2.6亿美元。

图：全球环氧塑封料市场规模（亿美元）



图：全球环氧塑封料对硅微粉的需求（亿美元）



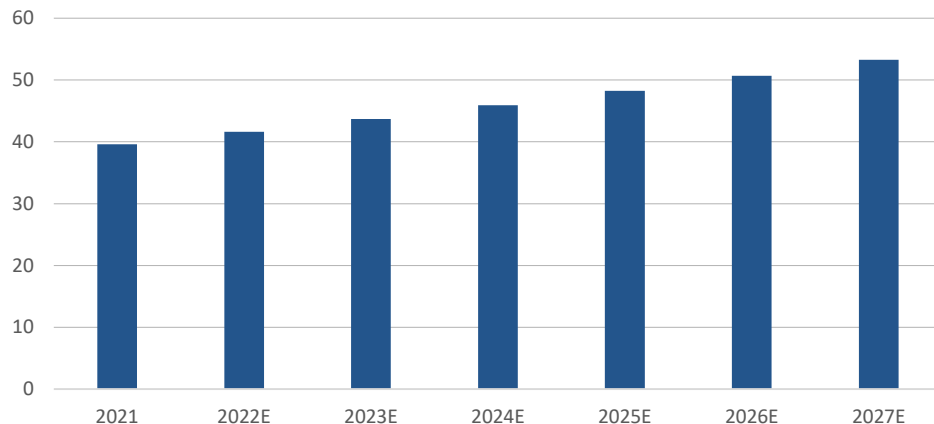
数据来源：Mordor Intelligence、海通国际

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2.3 全球硅微粉市场规模2027年有望达到53.3亿美元

- 受益于电动车及数据中心用电子元器件需求的快速增长，作为半导体工业重要的上游原材料，硅微粉市场规模有望随之不断增长。根据市场研究机构Mordor Intelligence的数据，2021年全球硅微粉市场规模约为39.6亿美元，预计到2027年有望增长至53.3亿美元，年均复合增长率5.1%。

图：全球硅微粉市场规模（亿美元）



数据来源：Mordor Intelligence，海通国际

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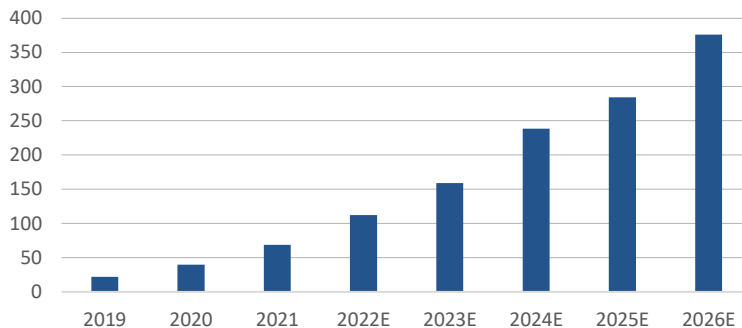
2.3 硅微粉产业有望受益于ChatGPT的兴起

- ChatGPT的发布给受困于消费电子下行的全球半导体业带来了新的增长动能。部署ChatGPT需要大量的算力以及存储空间，而且随着模型的迭代，对算力及存储空间的需求更是呈指数级增长。GPT、GPT-2和GPT-3的预训练数据量从5GB增加到45TB，GPT-3.5在训练中的总算力消耗则达到了3640PF-days，需要1万个高性能V100 GPU组成的高性能网络集群提供算力支撑。根据Omdia的数据，AI处理器的市场规模有望在2026年达到376亿美元，相对于2019年将飙升9倍，而ChatGPT带来的对存储芯片的增量需求也非常可观。由于硅微粉是半导体工业中不可或缺的材料，预期将受益于ChatGPT带来的对半导体芯片的增量需求。

表：历代GPT模型参数

模型	发布时间	参数量	预训练数据量
GPT	2018年6月	1.17亿	约5GB
GPT-2	2019年2月	15亿	40GB
GPT-2	2020年5月	1750亿	45TB

图：AI处理器市场规模预测（亿美元）



资料来源：微软、Omdia、海通国际

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2.4 硅微粉市场格局：日系厂商仍占主导地位

- ▶ 全球硅微粉龙头集中于日本，日本龙森、电化、新日铁三家公司的硅微粉产品在市场上占据了70%以上的市场份额，雅都玛公司则以其先进工艺在1微米以下球形硅微粉市场有着举足轻重的地位。随着世界半导体产业规模的不断扩大以及工艺制程进步对硅微粉要求的不断提高，预期上述公司硅微粉业务会有进一步的增长。

表：日本主要硅微粉生产企业概况

公司名称	简介	产品举例	品种	平均粒径 (μm)	下游厂商
龙森	专业从事二氧化硅填料的制造和销售，主要产品包括高纯结晶硅微粉、高纯熔融硅微粉、高纯球状硅微粉等。公司在日本、马来西亚、新加坡、美国等地拥有生产基地或分支机构。	Kikurosu MSR-04	球形	4.1	松下电工、日立化成
		FLB-1	熔融	1.1	
		RD-120	结晶	30	
电化	全球性化学工业企业，业务涵盖无机化学品、有机化学品和电子材料、医药等领域，旗下设有尖端功能材料部、电子部件材料部、多功能薄膜部和胶粘剂综合方案部，其中熔融硅微粉、球形硅微粉及球形氧化铝等产品由尖端功能材料部负责。	FB-1 SD	球形	1.5	松下电工、日立化成、住友电木
		SFP-10X	球形	0.3	
		SFP-30M	球形	0.3	
		FB-5SDX	球形	4.4	
新日铁纳米社	致力于半导体封装材料的研发、生产和供应，产品应用于大规模、超大规模集成电路封装及电子元器件、高压电器件的绝缘浇注、高级橡胶轮胎、高档油墨、涂料等领域。	FB-1SDX	球形	0.5	-
		HS-104	球形	27	
		HS-106	球形	19.5	
		HS-202	球形	16	
		HS-205	球形	8.5	
		HS-305	球形	85	
雅都玛	主要生产和销售球形硅微粉、球形氧化铝及相关衍生品，产品应用于超薄半导体封装料、LCD和PDP等的平板显示设备的隔膜密封材、汽车零部件为主的工程塑料、食品和医疗用品的包装薄膜等。	HS-301	球形	2.5	京瓷化学、日立化成、松下电工、三菱瓦斯化学、住友电木
		SE1050	熔融	-	
		S0-25H	球形	0.5	
		S0-C2	球形	0.5	
		S0-C3	球形	0.8	
		S0-25R	球形	0.5	
S0-32R	球形	1.5			

资料来源：公司公告，海通国际

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3.1 全球重点相关公司汇总

公司	21年收入 (亿元)	相关产品营收 占比	总市值 (亿元)	EBITDA (亿元)			EV/EBITDA		
				2021	2022	2023	2021	2022	2023
电化	200	-	135	29.9	33.2	32.0	8.8	6.6	5.9
联瑞新材	6.2471	88%	85.85	2.08	2.12	3.44	37.05	36.46	22.45
飞凯材料	26.2710	7%	115.83	6.33	7.09	8.04	17.27	15.42	13.59
雅克科技	37.8231	6%	272.75	6.08	9.09	12.14	43.64	29.20	21.86

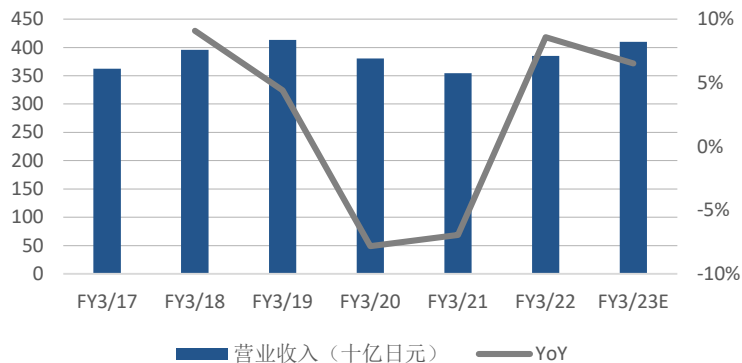
数据来源：公司公告、彭博、海通国际

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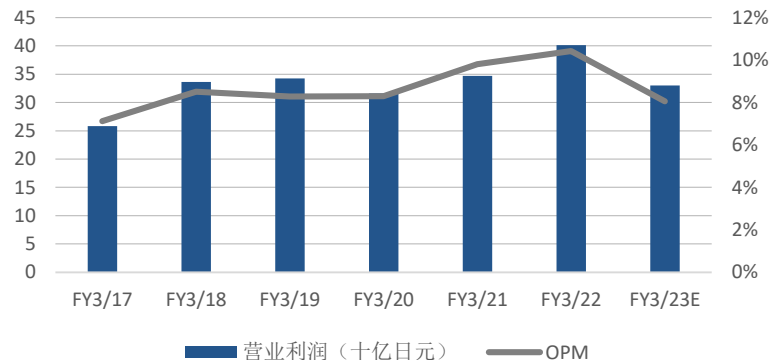
3.1.1 电化：全球硅微粉龙头企业

- 电化（4061.JP）是一家跨国化工企业，成立于1915年，总部位于日本东京都。电化的主要业务领域涵盖高性能材料、电子材料、化学品和电子设备等。目前电化公司的硅微粉业务在全球的市场份额约30%左右，位列全球第一。2022年3月财年，公司营业收入为3848亿日元，同比增长8.6%；营业利润401亿日元，同比增长15.5%，营业利润率为10.4%。公司预计，2023年3月财年营收为4100亿日元，同比增加6.5%，营业利润330亿日元，同比减少17.8%，营业利润率8.0%。

图：营收及增长率



图：营业利润及营业利润率



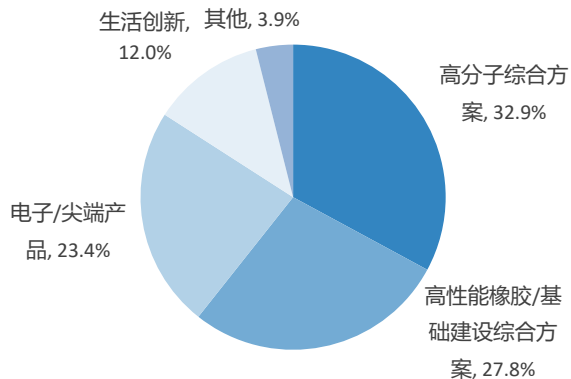
数据来源：公司公告、彭博、海通国际

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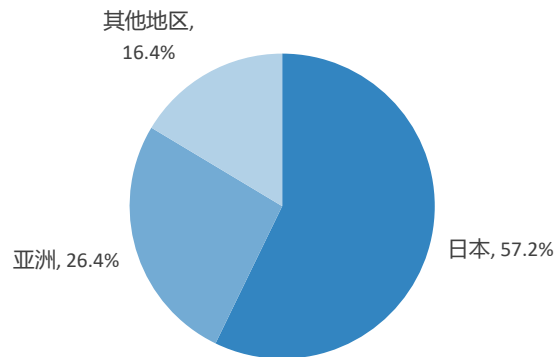
3.1.1 电化：全球硅微粉龙头企业

- 电化目前将其事业划分为四个部门：电子/尖端产品、生活创新、高性能橡胶/基础建设综合方案、高分子综合方案。电化的硅微粉业务隶属于电子/尖端产品部门，2022年3月财年该部门营收占公司营业收入的比例为23%。按地域划分，电化目前营收主要还是来自日本，占比57%；来自亚洲其他地区的营收占比26%，排行第二；除此之外的其他地区营收占比16%。

图：营业收入按业务划分（FY3/22）



图：营业收入按地域划分（FY3/22）



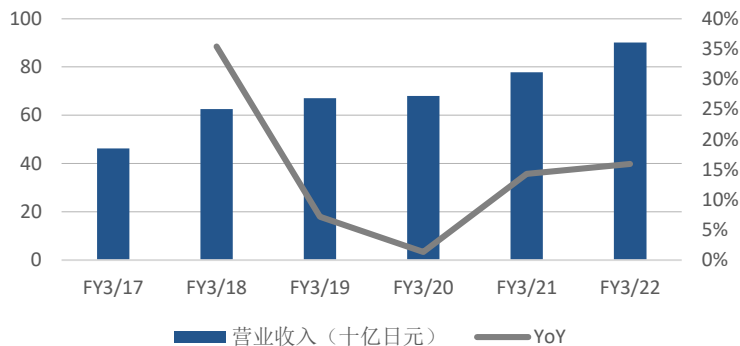
数据来源：公司公告、彭博、海通国际

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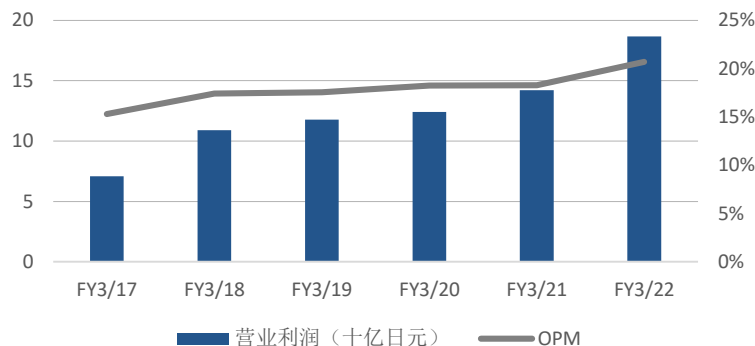
3.1.1 电化：全球硅微粉龙头企业

- 公司电子/尖端产品部门2022年3月财年营收902亿日元，同比上一财年增长了15.9%；营业利润187亿日元，同比上一财年增长31.3%，主要原因是2022年10月份之前公司相关产品供不应求，尽管能源价格上涨幅度较大，公司成功的转移了成本上涨的压力。公司该业务板块营收2017-2022的年均复合增长率为14.3%，营业利润的年均复合增长率约21.4%，成长性较好。

图：电子/尖端产品部门营业收入及增长率



图：电子/尖端产品部门营业利润及营业利润率



数据来源：公司公告、彭博、海通国际

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3.1.1 电化：全球硅微粉龙头企业

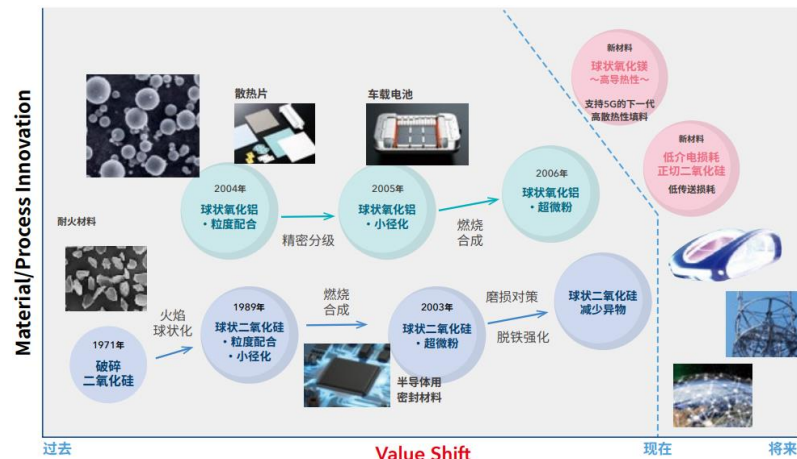
公司球形硅微粉业务的未来战略方向主要有两个：其一是聚焦半导体等高端市场，切实扩大公司产品在该领域中的应用。随着半导体制程的进步，半导体行业对硅微粉的纯度等要求也越来越高。公司目前正致力于开发新技术，以紧跟行业需求。其二是扩大产能。尽管近期需求有所减弱，但公司前年以及去年上半年，产品一直处于供不应求的状态。公司产能虽然一直在满负荷运转，但仍无法满足市场需求，因此丧失了进一步扩大市场份额的机会，公司未来想避免这种情况的再次发生。其三是公司拟紧跟市场发展方向，不断推出新产品。公司已经开始制作并同客户一起评估5G、6G所需的新产品。

表：电化电子/尖端产品业务SWOT分析

	描述
优势 (S)	通过丰富的产品线，满足客户多样化的需求；较高产品市场份额所带来的信息优势；高温控制技术、氮化技术、球状化技术、烧制技术等各方面的关键技术
劣势 (W)	市场技术扩大带来的设备投资负担的增加
机会 (O)	IoT和自动驾驶等通信领域对重要性和高速性不断提升的要求；xEV化等国家环保政策所带来的新商业机会
威胁 (T)	新材料所带来的市场洗牌的可能性；环保政策等因素导致的技术开发趋势的大转换；以新兴国企业为首的竞争对手的增加

数据来源：公司公告、海通国际

图：电化球状填料的历程

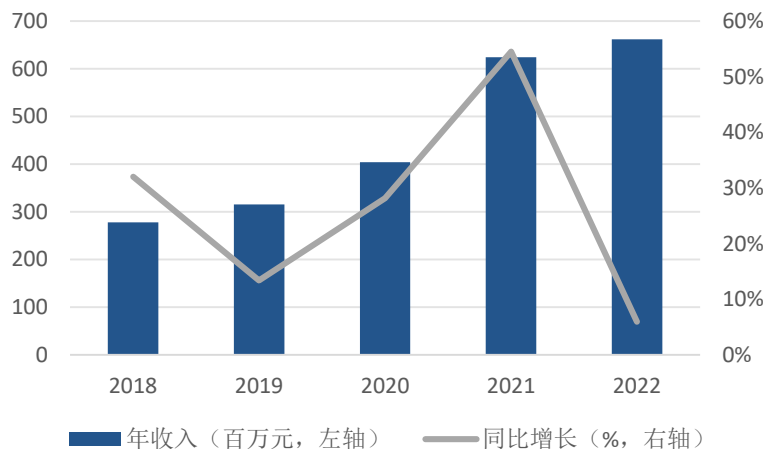


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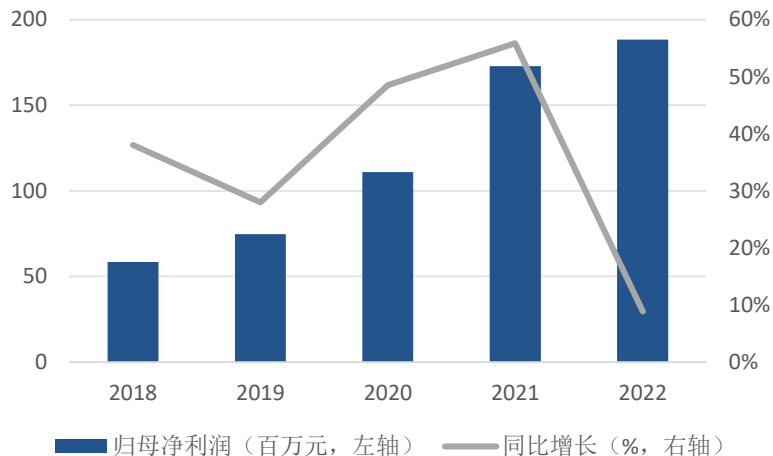
3.1.2 联瑞新材：深耕硅微粉行业，持续扩产强化竞争优势

- 联瑞新材（688300.SH）前身硅微粉厂成立于1984年，经三十多年的发展成为国内领先的硅微粉企业。公司产品作为一种性能优异的功能性陶瓷粉体填料，具有高纯度、高填充、高耐热、高绝缘、低线性膨胀系数、导热性好、介电损耗（Df）低等优良特性，产品应用于电子电路板、芯片封装材料、新型绝缘制品、导热界面材料、胶粘剂、蜂窝陶瓷等行业。2022年公司营业收入为6.62亿元，同比增长6%；净利润1.88亿元，同比增长9%。

图：营收及增长率



图：净利润及增长率



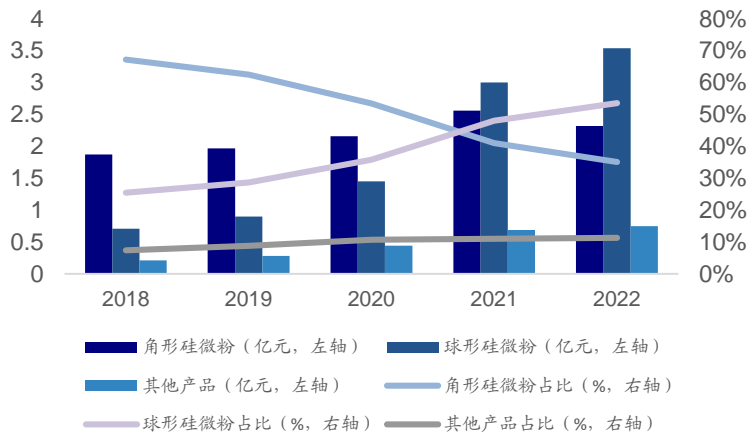
数据来源：公司公告、海通国际

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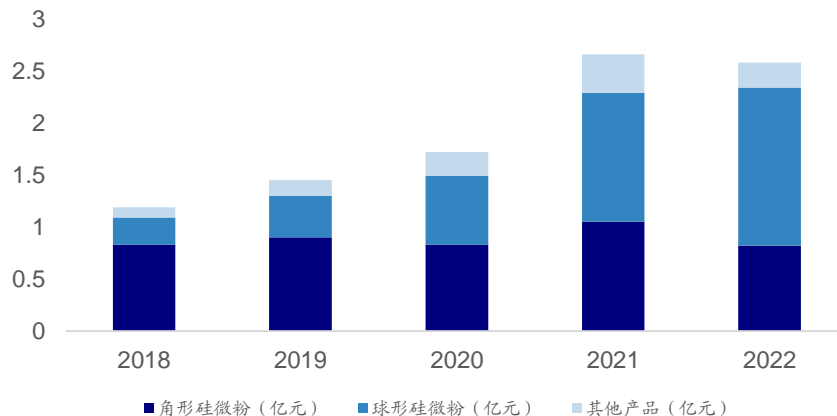
3.1.2 联瑞新材：深耕硅微粉行业，持续扩产强化竞争优势

- 球形硅微粉盈利占比持续提升。从收入结构来看，球形硅微粉2019-2022年收入分别为0.90、1.45、3、3.54亿元，营业收入占比从28.69%增长至53.49%；从毛利的结构看，球形硅微粉2019-2022年毛利分别为0.40、0.66、1.24、1.52亿元，毛利占比从27.64%增长至58.76%。

图：营业收入按产品划分（2018-2022年）



图：毛利润按产品划分（2018-2022年）



数据来源：海通国际整理

3.1.2 联瑞新材：深耕硅微粉行业，持续扩产强化竞争优势

- ▶ 公司布局高端球形硅微粉产品，快速扩张球形产品产能。公司应用于高频高速覆铜板需求的降低Df值的系列球形硅微粉、高端芯片封装需求的Low α 球形硅微粉、高导热环氧塑封料需求的Low α 球形氧化铝等产品销量持续提升。2022年全资子公司电子级新型功能性材料项目产线顺利运行、年产15000吨高端芯片封装用球形粉体生产线建设项目于2022年四季度顺利调试。

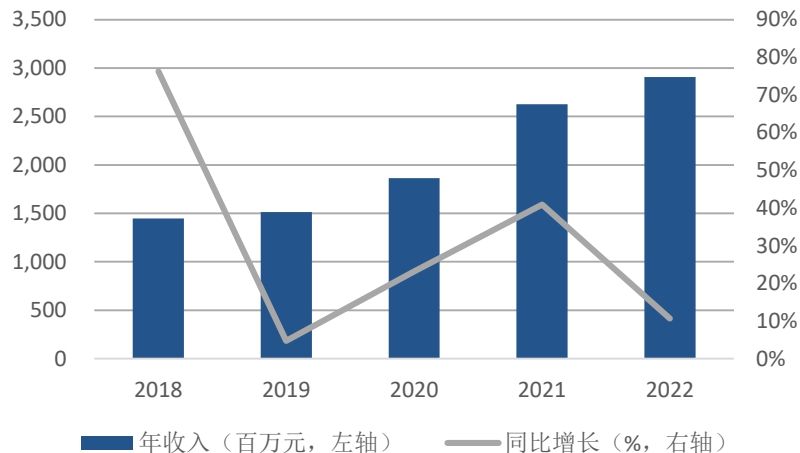
项目	投资总额	主要产品
硅微粉基地建设项目	1.1亿元	7200
电子级新型功能性材料项目	2.3亿元	生产球形氧化铝及液态填料9500吨/年
年产15000吨高端芯片封装用球形粉体生产线建设项目	2.3亿元	15000

数据来源：海通国际整理

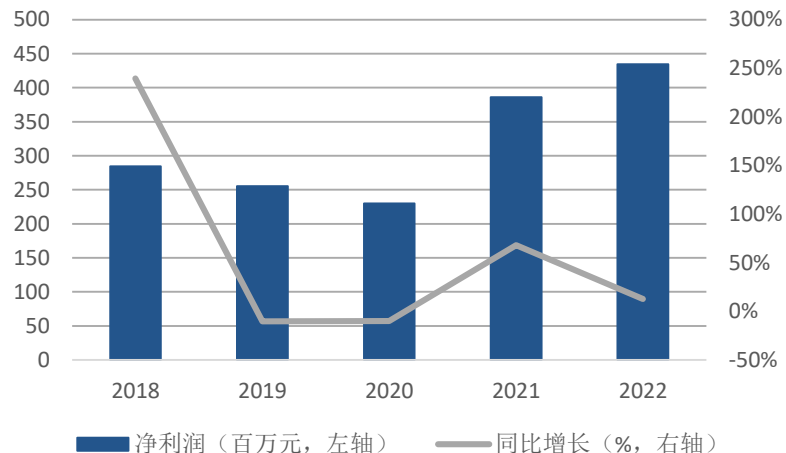
3.1.3 飞凯材料：收购长兴电子材料进军半导体封装材料领域

- ▶ 飞凯材料（300398）成立于2002年，公司主要从事电子化工材料的研发、生产和销售。公司四大主营产品分属屏幕显示材料、半导体材料、紫外固化材料以及有机合成材料四个应用领域。公司2017年收购昆山兴凯（长兴电子材料）60%股权。2022年飞凯材料的营业收入为29.07亿元，同比增长10.65%；净利润4.35亿元，同比增长12.62%。

图：2018-2022年公司营收及增长率



图：2018-2022年公司净利润及增长率



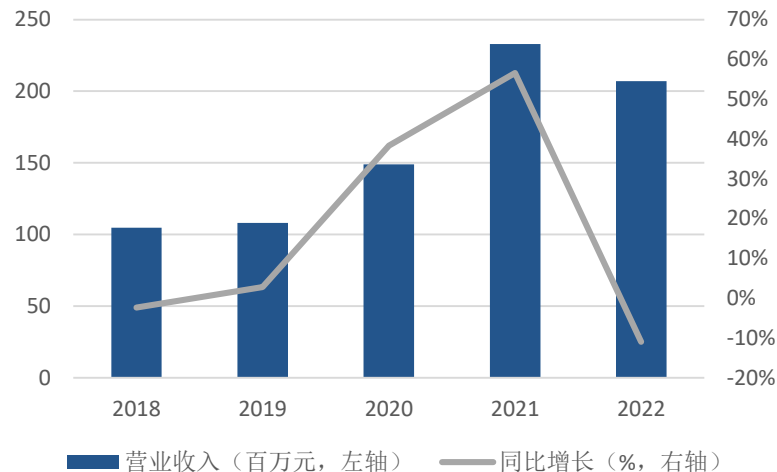
数据来源：公司公告、海通国际

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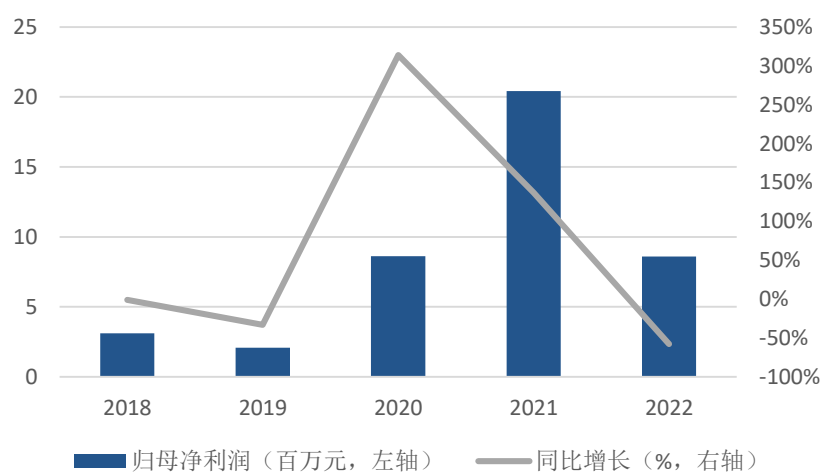
3.1.3 飞凯材料：收购长兴电子材料进军半导体封装材料领域

- 昆山兴凯长期致力于开发中高端器件及IC封装所需的材料，主要专业生产应用于半导体器件、集成电路等封装所需的环氧塑封料，可提供标准型、低应力型和高导热型等系列产品。2019-2022年昆山兴凯分别实现营业收入1.08、1.49、2.33、2.07亿元，同比增长2.75%、38.32%、56.62%、-11%；实现净利润208、862、2041、859万元，同比增长33%、314%、137%、-57.91%、。

图：昆山兴凯营业收入及增长率



图：昆山兴凯净利润及增长率



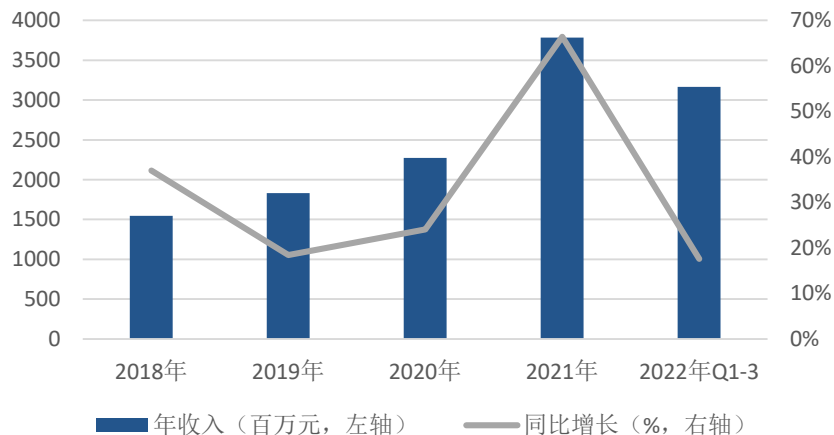
数据来源：公司公告、海通国际

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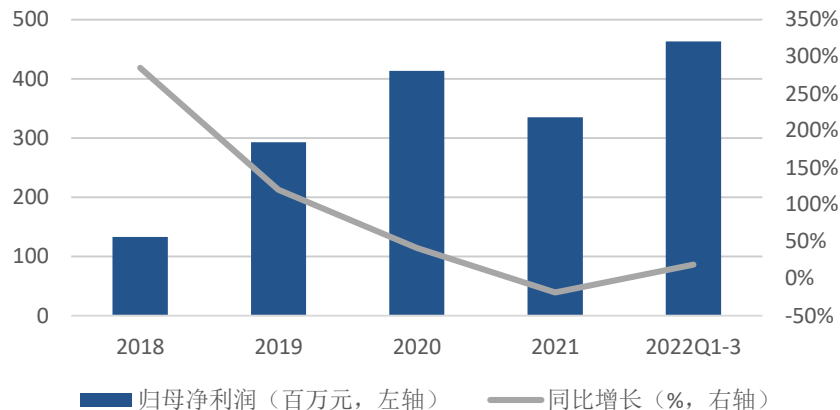
3.1.3 雅克科技：收购华飞电子布局半导体封装用硅微粉产品

- 雅克科技（002409）成立于1997年，公司产品主要包括电子材料、LNG保温绝热板材和阻燃剂。2016年12月，公司完成收购华飞电子100%股权，华飞电子主要从事电子封装用二氧化硅填料的生产、销售。2022年Q1-3公司实现营业收入31.67亿元，同比增长17.63%；实现净利润4.63亿元，同比增长18.88%。

图：雅克科技营收及增长率



图：雅克科技净利润及增长率



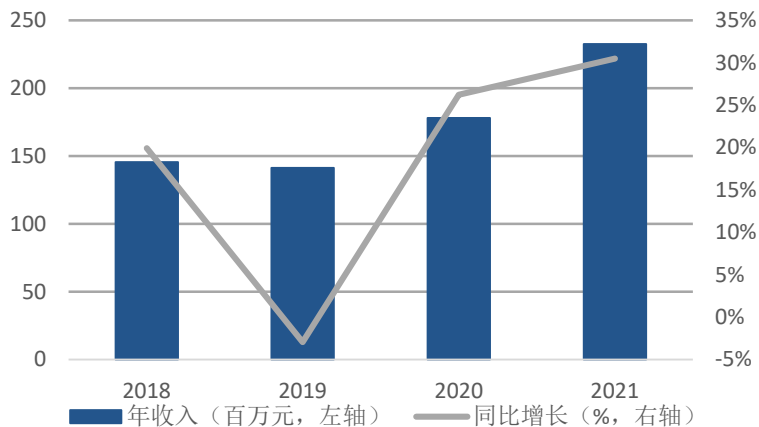
数据来源：公司公告、海通国际

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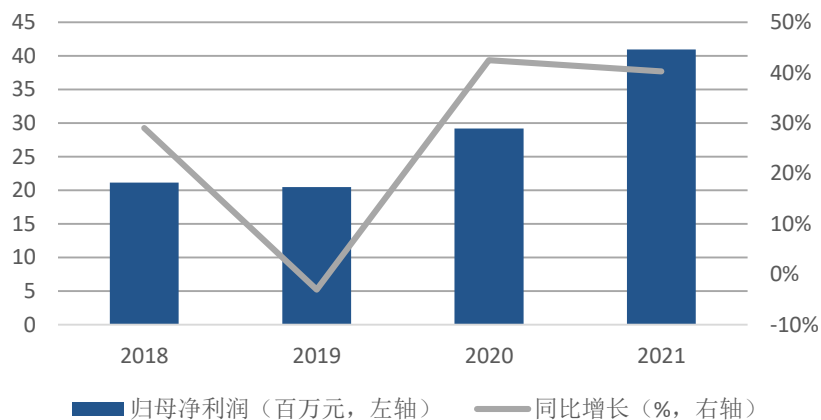
3.1.3 雅克科技：收购华飞电子布局半导体封装用硅微粉产品

- 华飞电子是国内领先的球形硅微粉生产商，华飞电子球形硅微粉主要销售给如住友电木、台湾义典、日立化成、德国汉高、松下电工等全球领先的塑封料生产企业。2021年华飞电子实现营业收入2.32亿元，同比增长30.50%；实现净利润0.41亿元，同比增长41.37%。

图：华飞电子营收及增长率



图：华飞电子净利润及增长率



数据来源：公司公告、海通国际

- Silica powder is a versatile class of inorganic non-metallic materials. Silica powder is a micron-sized powder obtained by physically or chemically crushing high-purity quartz ore, with particle size generally ranging from 1 to 100 microns. Silicon powder has excellent dielectric properties, low coefficient of thermal expansion, high thermal conductivity, high chemical stability, high temperature resistance, high hardness, etc. Therefore, it is widely used in semiconductor, electronics, chemical and pharmaceutical fields.
- Spherical silica powder are mostly used in high-end fields. Silica powder are generally classified into angular silica powder and spherical silica powder according to their particle morphology, and angular silica powder are often classified into crystalline silica powder and fused silica powder according to their crystallization characteristics, and spherical silica powder are usually further prepared on the basis of these two types of angular silica powder by flame balling and other methods. Compared with angular silica powder, spherical silica powder have better fluidity, higher filling in resin, lower internal stress, dimensional stability, lower coefficient of thermal expansion, and higher packing density and more uniform stress distribution, as well as reduced wear and tear on equipment and molds during the manufacturing of related products, thus gaining rapid application in high-end fields with higher performance requirements.
- High sphericity, high purity and ultra-fine are the future direction of spherical silica powder. The higher the sphericity, the better the fluidity and dispersion of the powder, the more uniform the distribution in the resin, and the less the wear and tear on the mold. High purity is the most basic requirement for materials in electronic products, and the requirements in ultra-large scale integrated circuits are even more stringent. In addition to the low content of conventional impurity elements, it is also required that the content of radioactive elements be as low or absent as possible, otherwise the transmission speed and quality of electrical signals will be negatively affected. The thermal conductivity of spherical silicon powder is not as good as crystalline silicon powder, and the heat dissipation performance of ultra-large-scale integrated circuits is high due to the huge heat generation, and the ultra-fine silicon micronized powder can partially solve this problem due to better thermal conductivity.
- The global silicon powder market is expected to reach \$5.3 billion by 2027. With the growing demand for electronic components due to the growth of electric vehicles and data centers, we expect the global silicon powder market to reach \$5.3 billion in 2027, growing at a CAGR of approximately 5.1%.
- Demand for silicon powder is expected to benefit from the rise of ChatGPT, which requires a large amount of computing power and storage space for deployment and training, resulting in a large demand for logic chips and storage chips, especially for advanced process chips. As an important upstream raw material in the semiconductor industry, silicon powder, especially the high-end spherical silicon powder suitable for advanced process packaging, is expected to benefit.
- Key companies. International companies still occupy a major position in the high-end silicon powder market, its market share and technology are more advanced, is now closely following the needs of the downstream industry, and continue to develop new technologies and new products. We recommend to focus on Denka. For Chinese companies, we recommend to focus on Novoray Corporation, Phichem Corporation, and Jiangsu Yoke Technology.
- Risks. Growth rate of data center is less than expected; time of semiconductor cyclical downturn is longer than expected; Growth rate of electronics for EV is less than expected.

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中性，未来12-18个月内预期相对基准指数变化不大，基准定义如下。根据FINRA/NYSE的评级分布规则，我们会将中性评级划入持有这一类别。

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Analyst Stock Ratings

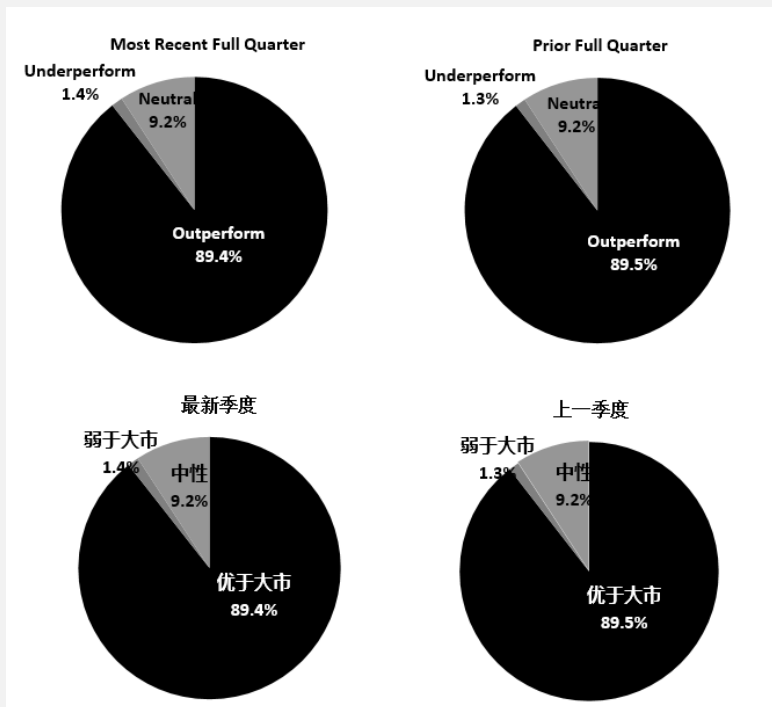
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评级分布 Rating Distribution



截至2022年9月30日海通国际股票研究评级分布

	优于大市	中性 (持有)	弱于大市
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投资银行客户*	5.5%	6.8%	4.5%

*在每个评级类别里投资银行客户所占的百分比。

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买入，未来12-18个月内预期相对基准指数涨幅在10%以上，基准定义如下

中性，未来12-18个月内预期相对基准指数变化不大，基准定义如下。根据FINRA/NYSE的评级分布规则，我们会将中性评级划入持有这一类别。

卖出，未来12-18个月内预期相对基准指数跌幅在10%以上，基准定义如下

各地股票基准指数：日本 – TOPIX, 韩国 – KOSPI, 台湾 – TAIEX, 印度 – Nifty100; 其他所有中国概念股 – MSCI China.

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	Outperform	Neutral (hold)	Underperform
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IB clients*	5.5%	6.8%	4.5%

*Percentage of investment banking clients in each rating category.

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SELL: The stock's total return over the next 12-18 months is expected to be below the return of its relevant broad market benchmark, as indicated below.

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